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MARKING

TinyLogic UHS Dual Inverting Buffer with 3-STATE Outputs

NC7WZ240

Description

The NC7WZ240 is a Dual Inverting Buffer with independent active LOW enables for the 3–STATE outputs. The Ultra High Speed device is fabricated with advanced CMOS technology to achieve superior switching performance with high output drive while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over the 1.65 V to 5.5 V V_{CC} operating range. The inputs and outputs are high impedance when V_{CC} is 0 V. Inputs tolerate voltages up to 5.5 V independent of V_{CC} operating range. Outputs tolerate voltages above V_{CC} when in the 3–STATE condition.

Features

- Space Saving US8 Surface Mount Package
- MicroPak[™] Pb-Free Leadless Package
- Ultra High Speed: t_{PD} = 2.3 ns Typ. into 50 pF at 5 V V_{CC}
- High Output Drive: ±24 mA at 3 V V_{CC}
- Broad V_{CC} Operating Range: 1.65 V to 5.5 V
- Matches the Performance of LCX when Operated at 3.3 V V_{CC}
- Power Down High Impedance Inputs / Outputs
- Overvoltage Tolerant Inputs Facilitate 5 V to 3 V Translation
- Outputs are Overvoltage Tolerant in 3-STATE Mode
- Proprietary Noise / EMI Reduction Circuitry Implemented
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

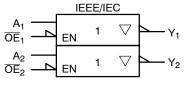
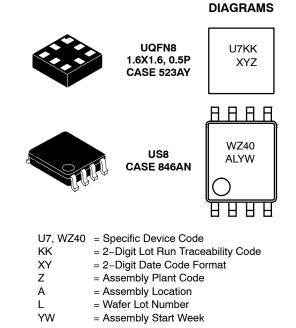


Figure 1. Logic Symbol



ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet. NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 6.

Connection Diagrams

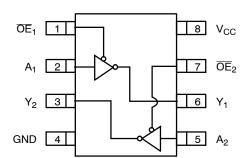
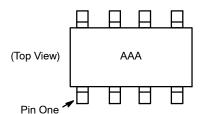


Figure 2. Pin Assignments for US8 (Top View)



AAA represents Product Code Top Mark - see ordering code

NOTE: Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

Figure 3. Pin One Orientation Diagram

PIN DESCRIPTIONS

Pin Names	Description
ŌĒn	Enable Inputs for 3-STATE Outputs
A _n	Inputs
Y _n	3-STATE Outputs

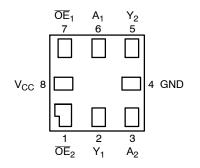


Figure 4. Pad Assignments for MicroPak (Top Thru View)

Inp	Inputs		
ŌĒ	A _n	Yn	
L	L	Н	
L	Н	L	
Н	L	Z	
Н	Н	Z	

H = HIGH Logic Level

L = LOW Logic LevelZ = 3-STATE



ABSOLUTE MAXIMUM RATINGS

Symbol	Parame	Min	Max	Unit	
V _{CC}	Supply Voltage	Supply Voltage		6.5	V
V _{IN}	DC Input Voltage (Note 1)		-0.5	6.5	V
V _{OUT}	DC Output Voltage		-0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	-	-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < 0 V	-	-50	mA
I _{OUT}	DC Output Source / Sink Current		-	±50	mA
I_{CC} / I_{GND}	DC V _{CC} / Ground Current	DC V _{CC} / Ground Current		±50	mA
T _{STG}	Storage Temperature Range	Storage Temperature Range		+150	°C
TJ	Junction Lead Temperature under	Junction Lead Temperature under Bias		+150	°C
ΤL	Junction Lead Temperature (Soldering, 10 Seconds)		-	+260	°C
PD	Power Dissipation in Still Air	US8	-	500	mW
		MicroPak-8	-	539	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

Symbol		Parameter	Min	Max	Unit
V _{CC}	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Rete	ntion	1.5	5.5	
V _{IN}	Input Voltage		0	5.5	V
V _{OUT}	Output Voltage	Active State	0	V _{CC}	V
		3-STATE	0	5.5	V
T _A	Operating Temperature		-40	+85	°C
t _r , t _f	Input Rise and Fall Time	V_{CC} @ 1.8 V ±0.15 V, 2.5 V ±0.2 V	0	20	ns/V
		V _{CC} @ 3.3 V ±0.3 V	0	10	
		V _{CC} @ 5.0 V ±0.5 V	0	5	
θ_{JA}	Thermal Resistance	US8	-	250	°C/W
		MicroPak-8	-	232	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

2. Unused inputs must be held HIGH or LOW. They may not float.



DC ELECTICAL CHARACTERISTICS

					Т	T _A = +25°C			T _A = −40 to +85°C				
Symbol	Parameter	Conc	litions	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit			
V_{IH}	HIGH Level Input			1.65 to 1.95	0.65 V _{CC}	-	-	0.65 V _{CC}	-	V			
	Voltage			2.3 to 5.5	0.7 V _{CC}	-	-	0.7 V _{CC}	_				
V _{IL}	LOW Level Input			1.65 to 1.95	-	-	0.35 V _{CC}	-	0.35 V _{CC}	V			
	Voltage			2.3 to 5.5	-	-	0.3 V _{CC}	-	0.3 V _{CC}				
V _{OH}	HIGH Level Output	V _{IN} = V _{IH} or	I _{OH} = -100 μA	1.65	1.55	1.65	-	1.55	_	V			
	Voltage	VIL		2.3	2.2	2.3	-	2.2	-				
					3.0	2.9	3.0	-	2.9	-			
				4.5	4.4	4.5	-	4.4	-				
				I _{OH} = -4 mA	1.65	1.29	1.52	-	1.29	-			
			I _{OH} = -8 mA	2.3	1.9	2.15	-	1.9	-				
				I _{OH} = -16 mA	3.0	2.4	2.80	-	2.4	-			
				I _{OH} = -24 mA	I _{OH} = -24 mA	3.0	2.3	2.68	-	2.3	-		
		I _{OH} = -32 mA	4.5	3.8	4.20	-	3.8	-					
V _{OL}	LOW Level Output Voltage	$V_{IN} = V_{IH}$ or	I _{OL} = 100 μA	1.65	-	0.0	0.10	-	0.10	V			
		voltage	voitage	voitage	ge V _{IL}		2.3	-	0.0	0.10	-	0.10	
				3.0	-	0.0	0.10	-	0.10	1			
				4.5	-	0.0	0.10	-	0.10				
			I _{OL} = 4 mA	1.65	-	0.08	0.24	_	0.24				
			I _{OL} = 8 mA	2.3	-	0.10	0.3	_	0.3	1			
			I _{OL} = 16 mA	3.0	-	0.15	0.4	_	0.4				
			I _{OL} = 24 mA	3.0	-	0.22	0.55	-	0.55				
			I _{OL} = 32 mA	4.5	-	0.22	0.55	-	0.55				
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V, G	ND	1.65 to 5.5	_	-	±0.1	_	±1	μA			
I _{OZ}	3–STATE Output Leakage			1.65 to 5.5	_	-	±0.5	_	±5	μA			
I _{OFF}	Power Off Leakage Current	V _{IN} or V _{OUT} =	V _{IN} or V _{OUT} = 5.5 V		-	_	1	-	10	μA			
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5 V, GI	ND	1.65 to 5.5	-	-	1	-	10	μA			

NOISE CHARACTERISTICS

				T _A = +25°C		
Symbol	Parameter	Conditions	V _{CC} (V)	Тур	Max	Unit
V _{OLP} (Note 3)	Quiet Output Maximum Dynamic V _{OL}	C _L = 50 pF	5.0	-	1.0	V
V _{OLV} (Note 3)	Quiet Output Minimum Dynamic V _{OL}	C _L = 50 pF	5.0	-	1.0	V
V _{OHV} (Note 3)	Quiet Output Minimum Dynamic V _{OH}	C _L = 50 pF	5.0	-	4.0	V
V _{IHD} (Note 3)	Minimum HIGH Level Dynamic Input Voltage	C _L = 50 pF	5.0	-	3.5	V
V _{ILD} (Note 3)	Maximum LOW Level Dynamic Input Voltage	C _L = 50 pF	5.0	-	1.5	V

3. Parameter guaranteed by design.



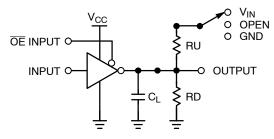
AC ELECTRICAL CHARACTERISTICS

				T _A = +25°C			T _A = −40 to +85°C									
Symbol	Parameter	Conditions	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit							
t _{PLH} , t _{PHL}	Propagation Delay	C _L = 15 pF	1.8 ±0.15	-	-	12.0	-	13.0	ns							
	A _n to Y _n (Figure 5, 7)	R _D = 1 MΩ S1 = Open	2.5 ±0.2	-	-	7.5	-	8.0								
			3.3 ±0.3	-	-	5.2	-	5.5								
			5.0 ±0.5	-	-	4.5	-	4.8								
		$C_{L} = 50 \text{ pF},$	3.3 ±0.3	-	-	5.7	-	6.0								
		R _D = 500 Ω S1 = Open	5.0 ±0.5	-	-	5.0	-	5.3								
t _{OSLH} , t _{OSHL}	SHL Output to Output Skew (Note 4) (Figure 5, 7)	$C_{L} = 50 \text{ pF},$	3.3 ±0.3	-	-	1.0	-	1.0	ns							
(Note 4) (Figure 5, 7)		e 5, 7) R _D = 500 Ω S1 = Open	5.0 ±0.5	-	-	0.8	-	0.8								
t _{PZL} , t _{PZH}	Output Enable Time	$\begin{array}{l} C_L = 50 \ \text{pF} \\ R_D, R_U = 500 \ \Omega \\ S1 = \text{GND for } t_{\text{PZH}} \\ S1 = V_I \ \text{for } t_{\text{PZL}} \\ V_I = 2 \ x \ V_{CC} \end{array}$	1.8 ±0.15	-	-	14.0	-	15.0	ns							
	(Figure 5, 7)		S1 = GND for t_{PZH} S1 = V _I for t_{PZL}	2.5 ±0.2	_	-	8.5	-	9.0							
					3.3 ±0.3	-	-	6.2	-	6.5						
								5.5 ±0.5	-	-	5.5	-	5.8			
t _{PLZ} , t _{PHZ}	Output Disable Time	$C_L = 50 \text{ pF}$	1.8 ±0.15	_	-	12.0	-	13.0	ns							
	(Figure 5, 7)	$R_D, R_U = 500 \Omega$ S1 = GND for t _{PZH}	2.5 ±0.2	-	-	8.0	-	8.5								
		S1 = V_I for t_{PZL}	S1 = V _I for t _{PZL} V _I = 2 x V _{CC}	S1 = V _I for t _{PZL} V _I = 2 x V _{CC}	S1 = V _I for t_{PZL} V _I = 2 x V _{CC}	S1 = V _I for t_{PZL} V _I = 2 x V _{CC}	S1 = V _I for t_{PZL} V _I = 2 x V _{CC}	$S1 = V_{I} \text{ for } t_{PZL}$ $V_{I} = 2 \times V_{CC}$	$S1 = V_I \text{ for } t_{PZL}$ $V_I = 2 \times V_{CC}$	3.3 ±0.3	-	-	5.7	-	6.0	
									5.0 ±0.5	-	-	4.7	-	5.0		
C _{IN}	Input Capacitance		0	_	2.5	-	-	-	pF							
C _{OUT}	Output Capacitance		5.0	-	4	-	-	-	pF							
C _{PD}	Power Dissipation	(Note 5)	3.3	-	10	-	-	-	pF							
	Capacitance (Figure 6)		5.0	-	12	-	-	-								

4. Parameter guaranteed by design. t_{OSLH} = |t_{PLHmax} - t_{PLHmin}|; t_{OSHL} = |t_{PHLmax} - t_{PHLmin}|.
5. C_{PD} is defined as the value of the increase equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (see Figure 6) C_{PD} is related to I_{CCD} dynamic operating current by the expression: $I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CC} static).$

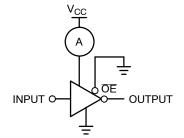


AC Loading and Waveforms



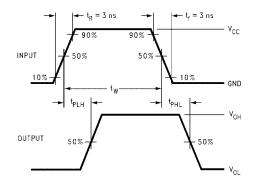
 C_L includes load and stray capacitance Input PRR = 1.0 MHz; t_W = 500 ns

Figure 5. AC Test Circuit



Input = AC Waveform; $t_r = t_f = 1.8$ ns; PRR = 10 MHz; Duty Cycle = 50%.

Figure 6. I_{CCD} Test Circuit



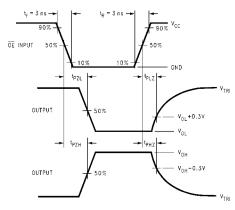


Figure 7. AC Waveforms

ORDERING INFORMATION

Order Number	Top Mark	Package	Shipping [†]
NC7WZ240K8X	WZ40	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ240L8X	U7	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel

DISCONTINUED (Note 7)

NC7WZ240K8X-L22236	WZ40	8-Lead US8, JEDEC MO-187, Variation CA 3.1 mm Wide	3000 / Tape & Reel
NC7WZ240L8X-L22185	U7	8-Lead MicroPak, 1.6 mm Wide (Pb-Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

6. Pb-Free package per JEDEC J-STD-020B.

7. **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on <u>www.onsemi.com</u>.

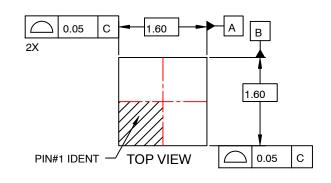
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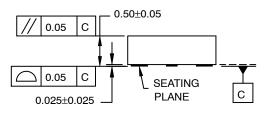




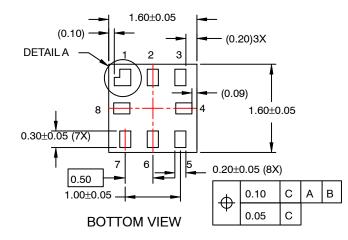
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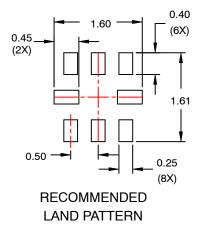
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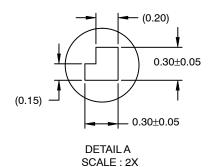
SIDE VIEW





NOTES:

- A. PACKAGE CONFORMS TO JEDEC MO-255 VARIATION UAAD.
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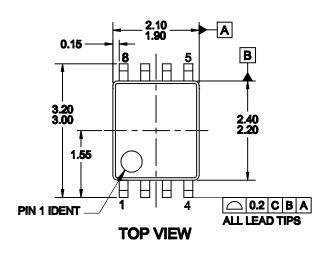
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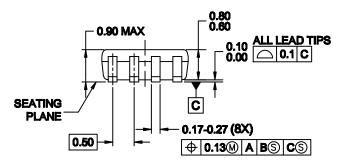
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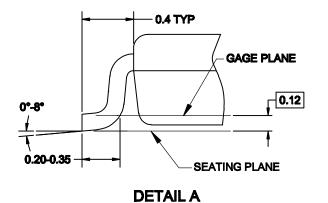
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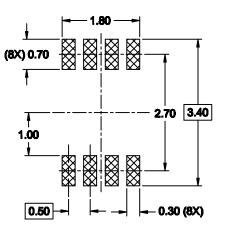
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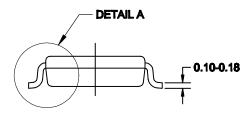




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